

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Chao-Yuan Su, et al.	§	Docket No.:	24061.59
		§		(TSMC2003-0121)
Serial No.:	10/822,961	§		
		§	Examiner:	Luan C. Thai
Filing Date:	April 13, 2004	§		
		§	Art Unit:	2891
For:	Microelectronics Package Assembly	§		
	Tool and Method of Manufacture	§	Conf. No.:	3593
	Thereof	§		

**RESPONSE TO NOTICE OF DRAWING INCONSISTENCY WITH SPECIFICATION**

Mail Stop: Issue Fee  
ATTN: Office of Patent Publication/Publishing Division  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Notice of Drawing Inconsistency with Specification mailed on April 14, 2006, Applicants amends the specification as follows.

**Amendments to the Specification** begins on page 2 of this paper.

**Remarks** begin on page 3 of this paper.

**In the Specification**

Please add the following paragraph after Paragraph [0007] under “Brief Description of the Drawings” section as follows:

Fig. 4 illustrates a sectional view of another embodiment of a microelectronic package assembly tool constructed according to aspects of the present disclosure.

**Remarks**

In accordance with the Notice of Drawing Inconsistency with Specification, Applicants have amended the Brief Description of Drawings Section of the specification to include Figure 4, which was inadvertently omitted. No new matter has been added. Payment of the Issue Fee is being simultaneously filed and therefore, Applicants respectfully request that the application proceed to grant.

Applicant believes no fee is due. However, the Commissioner is hereby authorized to charge any deficiency fees or credit any overpayments associated with this communication to Deposit Account No. 08-1394.

Respectfully submitted,



David M. O'Dell

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Dated: May 12, 2006

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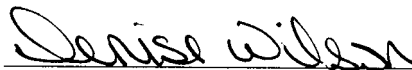
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IP Facsimile: 214-200-0853

File: 24061.59

**CERTIFICATE OF TRANSMISSION**

I hereby certify that this correspondence is being electronically filed with the U.S. Patent and Trademark Office via EFS-Web System on May 12, 2006.



Denise M. Wilson